IN THE SPECIFICATION

Please replace the paragraph beginning at page 10, line 9 with the following:

A1

As shown in Fig. 7C, the sealing resin 6 is supplied to a central section of the mounting area on the substrate 1. For this purpose, the present invention employs a one-point coating by a known dispenser. The sealing resin 6 is an epoxy-based instantaneous thermosetting resin of which a ratio of contraction is larger than a ratio of thermal expansion of cured sealing resin. The sealing resin 6 is completely set or hardened in about 30 seconds at 200 °C. The sealing resin 6 is supplied on the substrate 1 by the one-point coating. The supplied resin 6 is in a contour of an approximately [hemispherical shape by surface tension of the resin 6.

Please replace the paragraph beginning at page 11, line 23 with the following:

A2

In the embodiments of Figs. 4 and 5, on an inner edge of the solder resist 2 disposed in a peripheral section of the substrate 1, the mounting pad 3 is formed in parallel with each associated one of the inner edges respectively in four directions. In the embodiment of Fig.4, on an inner side of each section of the mounting pad 3, a solder resist 2 is formed in parallel therewith. In the embodiment shown in Fig. 5, on the inner side of each section of the mounting pad 3, a solder resist 2 is formed in a trapezoidal contour. In a trapezoid 8, an upper edge 9 on the side of a central section of the substrate 1 is shorter than a lower edge 10 on the side of the pad 3 and the upper and lower edges 9, 10 are parallel to the pad 3.

Please replace the paragraph beginning at page 12, line 4 with the following: